## fischer elektronik 23

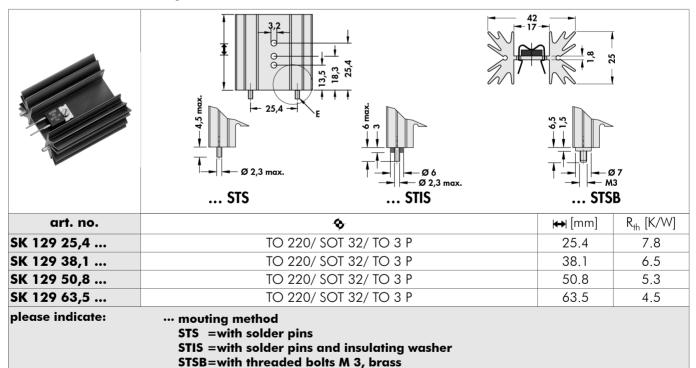
## **Extruded heatsinks for PCB mounting**

for semiconductor clip-mounting

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art. no.	♦	I⇔I [mm] R <sub>th</sub> [K/W]
SK 129 25,4	TO 220	25.4 7.8
SK 129 38,1	TO 220	38.1 6.5
SK 129 50,8	TO 220	50.8 5.3
SK 129 63,5	TO 220	63.5 4.5
please indicate:	••• mouting method STC  =with solder pins STIC =with solder pins and insulating washer	

 $\mathbf{P}$  = raised retaining stud,  $\mathbf{E}$  = mounting method special lengths and drillings on request surface treatment: black anodised

for semiconductor screw-mounting



 ${\bf P}=$  raised retaining stud,  ${\bf E}=$  mounting method

special lengths and drillings on request

surface treatment: black anodised

A 99

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A 90 A 89 **→** A 111 – 116 A 21

Attachable heatsinks for TO-cases	→ A 91
Mounting for TO 3 angle	→ A 121
Silicone wafers	→ E 2 – 4
Mica wafers	→ E 11

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